

S5AC THRU S5MC

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

Mechanical Data

Case: SMC

● Terminals: Solderable per MIL-STD-750, Method 2026

Approx. Weight: 0.22g / 0.0077oz



Pinning	
PIN	DESCRIPTION
1	Cathode
2	Anode

Absolute Maximum Ratings And Characteristics

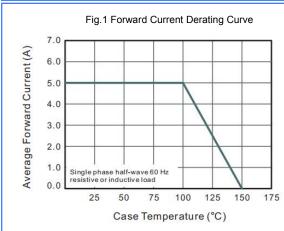
Ratings at 25°C ambient temperature unless otherwise specified.

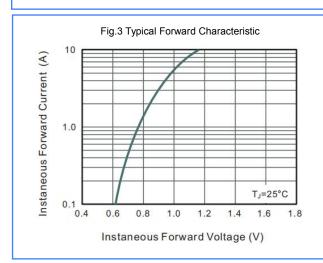
Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

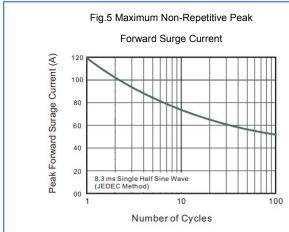
Parameter	Symbols	S5AC	S5BC	S5DC	S5GC	S5JC	S5KC	S5MC	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Tc = 125 °C	I _{F(AV)}	5						A	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I _{FSM}	120							А
Maximum Forward Voltage at 1 A	V _F	1.1						V	
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta =125 °C	I _R	5 100						μА	
Typical Junction Capacitance (1)	C _j	50							pF
Typical Thermal Resistance (2)	Reja Rejc	35 13						°C/W	
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150						°C	

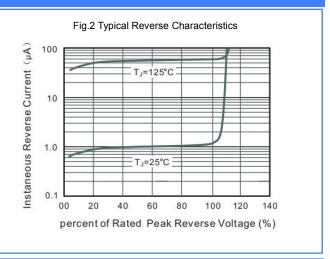
- (1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
- (2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

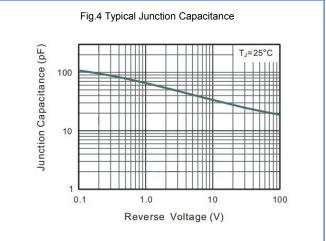










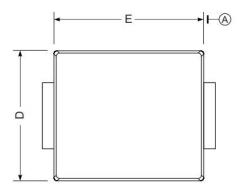


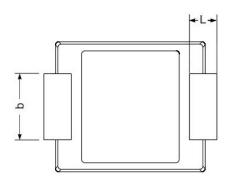


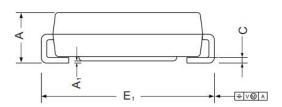
Package Outline

Plastic surface mounted package; 2 leads

SMC







UNIT		Α	С	D	E	E1	A 1	L	b
mm	max	2.62	0.31	6.2	7.0	8.0	0.21	1.6	3.25
	min	2.00	0.15	5.6	6.5	7.6	0.05	0.9	2.75
mil	max	103	12	244	276	315	8.3	63	128
	min	79	5.9	220	256	299	2.0	35	108

The recommended mounting pad size

